ECWC 14 Program

DAY ONE (4/25)

ECWC14
14th Electronic Circuit World Convention
25-27 April 2017, KINTEX, S. KOREA

11:00~11:10	Opening Ceremony		
11:10~12:10	Keynotes	**Packaging Technology in 2017 and Beyond** YoungChul Park, Amkor Technology Korea **Global Electronic Industry Supply Chain: Present & Future Market Dynamics** Walter Custer, Custer Consulting Group	
Lunch/Poster Session (12:10~13:00)			
	Room 305	Room 306	Room 307
	S1 Packaging/PCB Materials 1 (TPCA)	S2 Processing Technology 1 (IPC)	Short Course (13:00~15:30)
13:00~13:30	MAO-11 **Development of adhesive fluorocarbon powder for additive of high frequency and high speed PCB base materials** Wataru Kasai, Asahi Glass Co., Ltd.	PTO-11 **New, advanced soldermask and photoresist pretreatment for significant waste water benefits and low etch depth requirement** Wonjin Cho, Atotech (China) Chemicals Ltd	**Fan-Out Wafer-Level Packaging and 3D Packaging** John Lau, ASM Pacific Technology
13:30~14:00	MAO-12 **Ultra-Low Dk PCB Materials for High Speed Low loss applications** Martin Cotton, Ventec International Group	PTO-12 **Research on Process of Special Inlay Design** Lu Xiao, Shengyi Electronic Co., Ltd.	
14:00~14:30	MAO-13 **Novel low loss multilayer material for High speed application** Jeongdon Kwon, Doosan Corp. Electro-Materials BG	PTO-13 **Copper Electroplating of a Printed Circuit Board Using Reduced Graphene Oxide as a Conducting Layers** WeiYang Zang, National Chung Hsing University	
14:30~15:00	MAO-14 **R & D of a Novel Environment-friendly Copper Clad Laminate, which is decomposable and recyclable** Xingdi Jie, Shengyi Technology Co., Ltd.	PTO-14. **The production and application research of a special high-precision entry board used in back-drilling** Fei Liu, Shenzhen Newccess Industrial Co., Ltd	
Break/Poster Session (15:00~15:30)			
	S3 Management (EIPC)	S4 Testing/Reliability 1 (CPCA)	S5 High Speed PCB (IPC)
15:30~16:00	MGO-1 **Best Practices to Aid Enterprise Supply Chain Data Collection Challenges** Teresa Visto, WSP|Parsons Brinckerhoff	RLO-11 **The application of HPLC in the process of manufacturing process of copper clad laminate** Dan Li, Shengyi Technology Co., Ltd.	HSO-1 **Influence of Copper Conductor Surface Treatment for High Frequency PCB on Electrical Properties and Reliability.** Seiya Kido, MEC Company
16:00~16:30	MGO-2 **Preventing Corrosion of Electronic Components by Supply Chain Management** Christopher Muller, Purafil, Inc	RLO-12 **Characterization of Solder Spreading Effect by Thermal Treatment for Immersion Tin Plating of PCB** Jongkwan Jang, Hwabaek Engineering Co. Ltd.	HSO-2 **The study of Microstripline Impedance** Lijuan Hou, Kinwong Electronic (Shenzhen) Co., Ltd...
16:30~17:00	MGO-3 **Conflict Minerals: The Real Meaning of Due Diligence and the Advocacy** Teresa Visto, WSP|Parsons Brinckerhoff	RLO-13 **Quality factor of a printed circuit board affects the SMT-With emphasis on the automotive PCB** Heekyung Kim, Moriah Korea	
17:30~19:00	KPCA show and ECWC Joint Reception and Award Ceremony (5 best papers)		

DAY TWO (4/26)

ECWC14
14th Electronic Circuit World Convention
25-27 April 2017, KINTEX, S. KOREA

	Room 305	Room 306	Room 307
	S6 Packaging/PCB Materials 2 (TPCA)	S7 Processing Technology 2 (HKPCA)	S8 Embedding Technology (EIPC)
10:00~10:30	MAO-21 **Feasibility Studies and Development of High Reliability Photosensitive Solder Resist for IC Package** Tomoya Kudo, Taiyo Ink Mfg. Co., Ltd.	PTO-21 **An overview of Registration for Multilayer Printed Circuit Boards** Paul Walder, MIE Multiline International Europa L.P	EBO-1 **Sharing experience in Embedding of Active and Passive Components in Organic PCBs for more reliability and miniaturization.** Thomas Hofmann, Hofmann Leiterplatten GmbH
10:30~11:00	MAO-22 **Advance Research on Resin of Liquid Photosensitive Solder White Ink** Laixi Wu, Jiangsu Kuangshun	PTO-22 **Technology of Partial Hybrid Dielectric in Same Layer** Ping Zeng, Shenzhen Kinwong Electronic Co., Ltd.	EBO-2 **Automotive camera module using passive device embedded substrate** Hyunho Kim, KAIST
11:00~11:30	MAO-23 **UV/LED Light initiator and Photoresist curing research** Ping Lu, Jiangsu Kuangshun	PTO-23 **Thin substrate development trend in industry** Brandon Kim, K-Sol	EBO-3 **Analysis of power module based on embedded component technology** Lixing Huang, Shennan Circuits Co., Ltd.
Lunch/Poster Session (11:30~13:00)			
	S9 Printed Electronics (IPC)	S10 Testing/Reliability 2 (HKPCA ?)	FOWLP Forum (13:00~15:00) (CPCA)
13:00~13:30	PEO-1 **Laser Sintering of Cu Based Metal-Organic Decomposition Ink for Printed Electronics Application** Kyung-Tae Kang, Korea Inst. of Industrial Tech.	RLO-21 **Investigation on FR408HR Materials Inner Connect Reliability** Lipeng Wan, Shengyi Electronic Co., Ltd.	**Fan out Package innovations for future** Benson Lin, MediaTek
13:30~14:00	PEO-2 **Calixarene as additive fixing agent research on PCB production** Zhenquan Liu, Guangdong Chengde Elec.Tech Co., Ltd.	RLO-22 **Acceleration Test of Ion Migration in FR-4 Laminates** Hyekyoung Lee, Doosan Corp. Electro-Materials BG.	**Updated FOWLP development** Shuzo.Akejima, Toshiba
14:00~14:30	PEO-3 **Thermal Sintering of Inkjet-printed Silver Patterns by a Heated Gas Beam** Sang-Ho Lee, Korea Inst. of Industrial Tech.	RLO-23 **PCB Reliability problem on CAF and Pseudo CAF** Jinho Lee, Korea Electronics Technology Institute	
Break/Poster Session (14:30~15:30)			
	S11 Emerging Technology (TPCA)	Special Talk (15:00~16:00)	S13 HDI Technology (KPCA)
15:30~16:00	EMO-1 **Fabrication of Arbitrary 3D Metallic Microstructures on PDMS Substrate** Kuan-Ming Huang, National Taiwan University	**Four Essential Skills That Provided My Success In PCBs** Happy Holden, I-Connect007	HDO-1 **Development of the novel solder resist oriented towards HDI PCBs** Yanhong Zhang, Taiyo Ink Mfg. Co., Ltd
16:00~16:30	EMO-2 **Cu-Ag Nano-Alloy: Progress, Challenges and Opportunities** Xiaoqing Zhang, Zhuhai Topsun Electronic Technology Co., Ltd.	S12 Design/Modeling (IPC) DSO-1 **Unified data structure for describing PCB** SunHue Huh, Polliwog Corporation	HDO-2 **Manufacture of HDI printed circuit board with Rogers base material** Xinhong Su, Zhuhai Founder PCB Development Co. Ltd.
16:30~17:00	EMO-3 **Low Temperature, Pressureless Cu-to-Cu Bonding By Electroless Nickel Plating** Chun-Hsiang Yang, National Taiwan University	DSO-2 **Accuracy of Material Preparation** Dong Liu, Shenzhen Suntak Multilayer PCB	

DAY THREE (4/27)

ECWC14
14th Electronic Circuit World Convention
25-27 April 2017, KINTEX, S. KOREA

	Room 305	Room 306	Room 307
	S14 Packaging/PCB Materials 3 (TPCA)	S15 Process Technology 3 (KPCA)	PCB Technology FORUM (JPCA)
10:00~10:30	MAO-31 **Conformal Coatings Today and in the Future** Manfred Suppa, Lackwerke Peters GmbH & Co. KG	PTO-31 **The equipment for ultra thin board treatment** Kazuyoshi Nishimoto, C. Uyemura & Co., Ltd.	**FPC Market and related Technology Trend** Hirofumi Matsumoto, Nippon Mektron
10:30~11:00	MAO-32 **Technology trends in flexible circuits materials for smart phone application** Jeongmin Kweon, INNOX Corporation	PTO-32 **Research on Printed Circuit Board Mechanical Drilling** Chongyong Wang, Guangdong University of Technology	
11:00~11:30	MAO-33 **Development of Electric Insulating and Non-Cleaning Sn-3.0Ag-0.5Cu Solder Paste** Ashutosh Sharma, University of Seoul	PTO-33 **Patent application trend in PCB Field** Byungjo Min, Korean Intellectual Property Office	**TBD** Henry Utsunomiya, Interconnection Technologies
11:30~12:00	MAO-34 **Development of Super Adhesion Primer for Fine Pattern** HyeonJin Seo, Doosan Corp. Electro-Materials BG		
Lunch/Poster Session (12:00~13:00)			
	S16 Packaging Technology (TPCA)	S17 Testing/Reliability 3 (KPCA)	S18 Soldering (CPCA)
13:00~13:30	PKO-1 **Strong Effect of Plating Current Density on the Cu Pillar Microstructure and Its Adhesion with An ABF Substrate** YingSyuan Wu, Yuan Ze University	RLO-31 **Evaluation of the Anti-Creep Corrosion Capacity for ENIG PCB by Way of Accelerated Corrosion Verification Platform** Dem Lee, IST	ST0-1 **Solderability between Sn-3Ag-0.5Cu Alloy and Cu Pillars Deposited via Different Plating Current Densities** PeiTzu Lee, Yuan Ze University
13:30~14:00	PKO-2 **Controlling the Adhesion of Electroless Plating Ni-P Film on Si Wafer by Silane Compound Modification and Rapid Thermal Annealing** Wei-Yen Wang, National Tsing Hua University	RLO-32 **Research of factors affecting interface voids in IMAg PCBs** Zhiqiang Lu, Guangzhou Fastprint Circuit Tech Co.	STO-2 **Solder Wetting Behavior of Plasma Organic Surface Finish with Multiple Heat-Treatment** Kyoung-Ho Kim, Korea Institute of Industrial Technology
14:00~14:30	PKO-3 **Study on A Formulated No Clean Flux For Fine-Pitch Flip Chip Package of Copper Pillar/ Microbump Interconnect** Ya-Ching Chuang, Shenmao Technology Inc.	RLO-33 **Flexibility Test Method for Optic-Electric FPCB** Young-Min Im, Korea Electronics Technology Institute	STO-3 **Interfacial Microstructures of Solder Joints on ENIG and ENEPIG Surface Finishes with Metal Turnover of Ni Plating Solution** Wonil Seo, Korea Institute of Industrial Technology
Break (14:30~15:00)			
15:00~15:30	Closing Ceremony		

Registration Fee

REGISTRATION

Unit: KRW (USD)

Type	One day	Two days	Three days
WECC Member	165,000 ($150)	231,000 ($210)	297,000 ($270)
Non-member	231,000 ($210)	319,000 ($290)	418,000 ($380)
Chair/Speaker	free	132,000 ($120)	187,000 ($170)
Student	110,000 ($100)	154,000 ($140)	198,000 ($180)